

# Column Parallel CCD and Raw Charge Storage Pixels by LCFI

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for LCFI collaboration

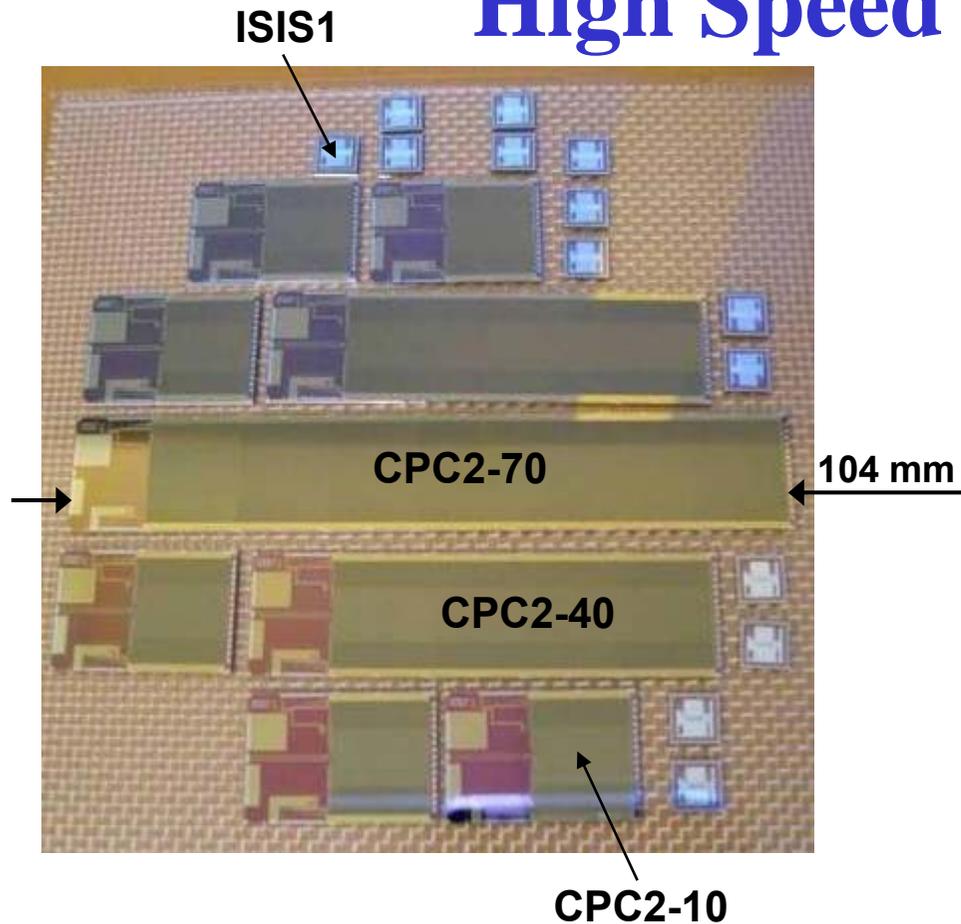
LCWS2008, 17 November 2008

# Outline

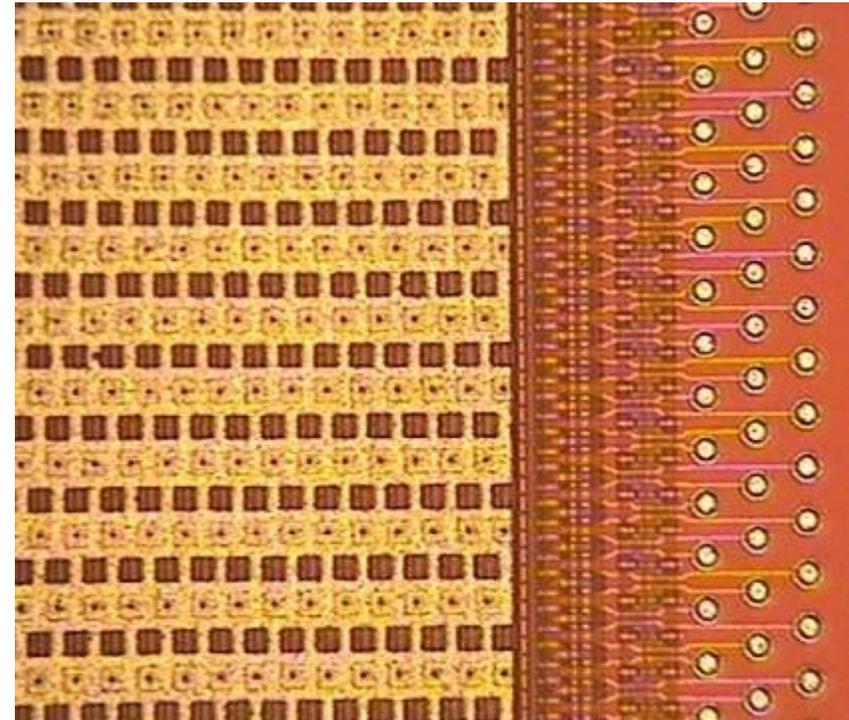
- Column Parallel CCD
  - ◆ Sensor: CPC2
  - ◆ Readout ASIC : CPR2A
  - ◆ CPCCD with reduced capacitance : CPC-T
- Raw charge storage pixels: ISIS2

# CPCCD Sensor: CPC2

# High Speed CPCCD



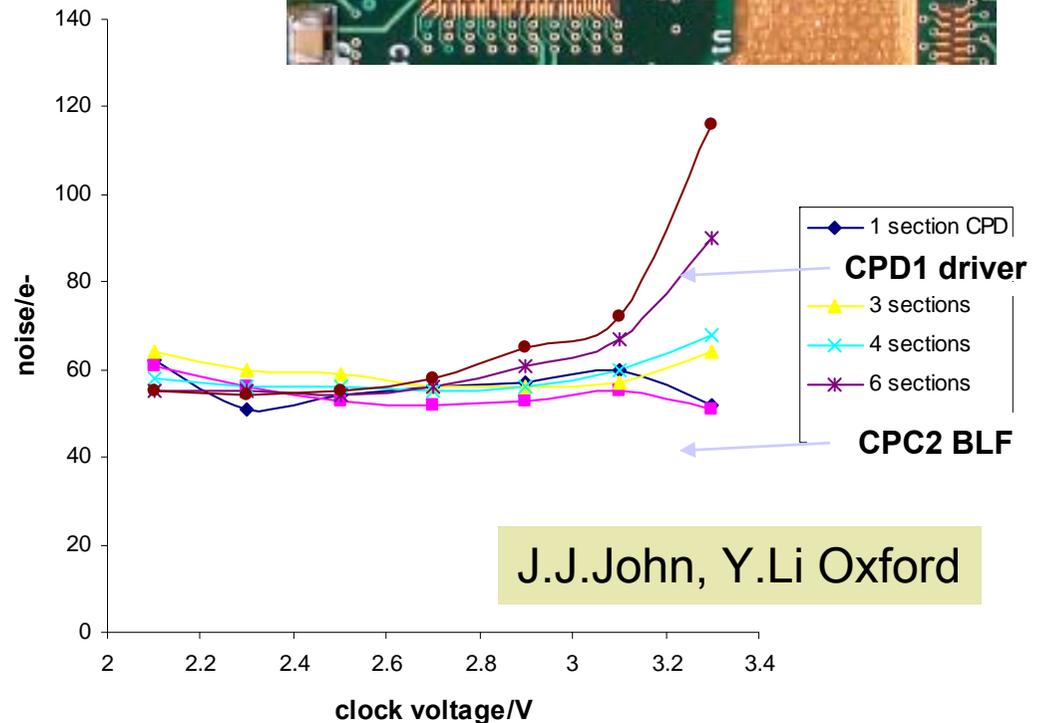
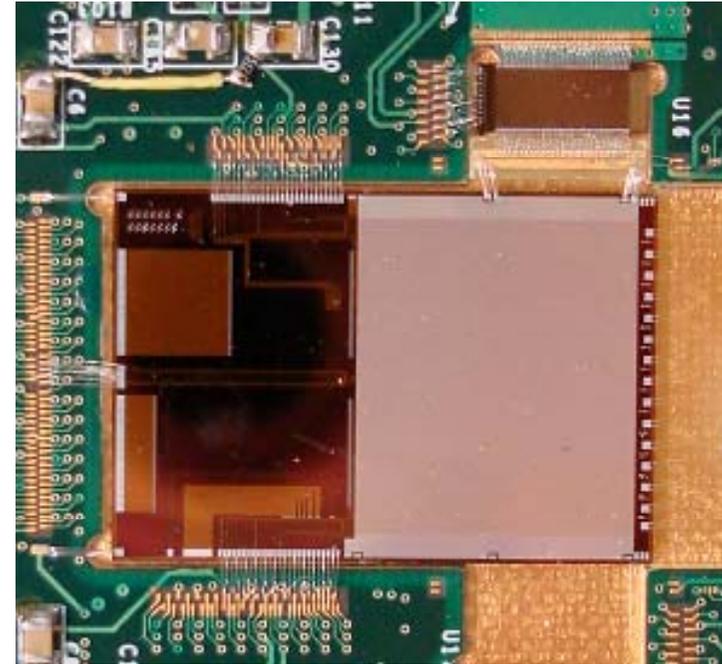
Busline-free CPC2



- High speed (busline-free) devices with 2-level metal clock distribution
- Whole image area serves as a distributed busline
- Designed to reach 50 MHz operation

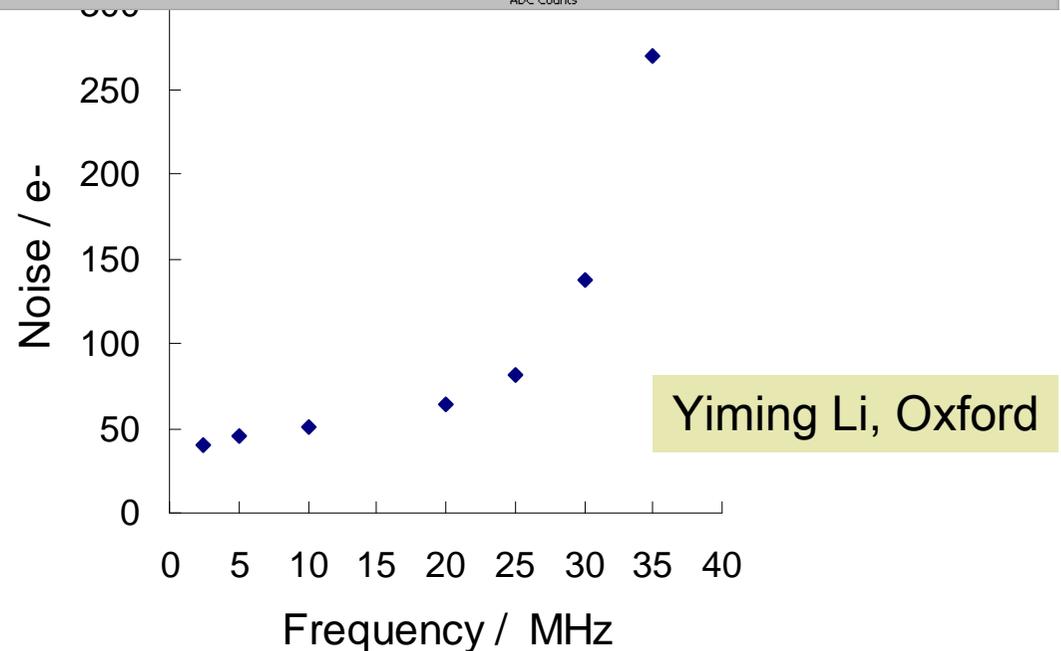
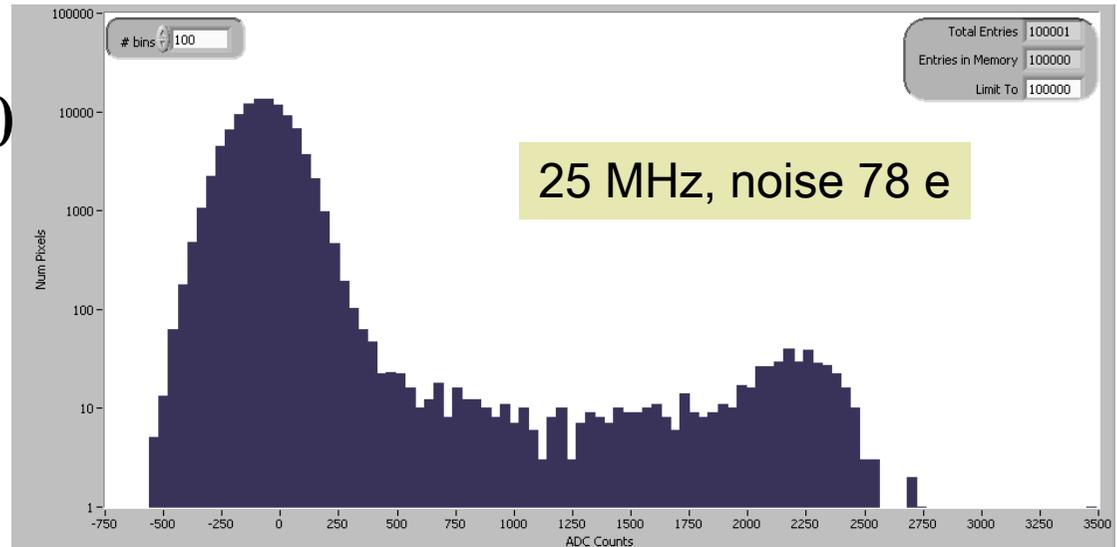
# Tests of high speed CPC2

- Need CPD1 driver chip to drive high speed CPC2
- Assembled several CPC2-10 and CPC2-40 with CPD1
- CPC2 noise performance optimized using CPD1 handles
  - ◆ # CPD1 sections
  - ◆ Clock voltage



# Maximum Frequency

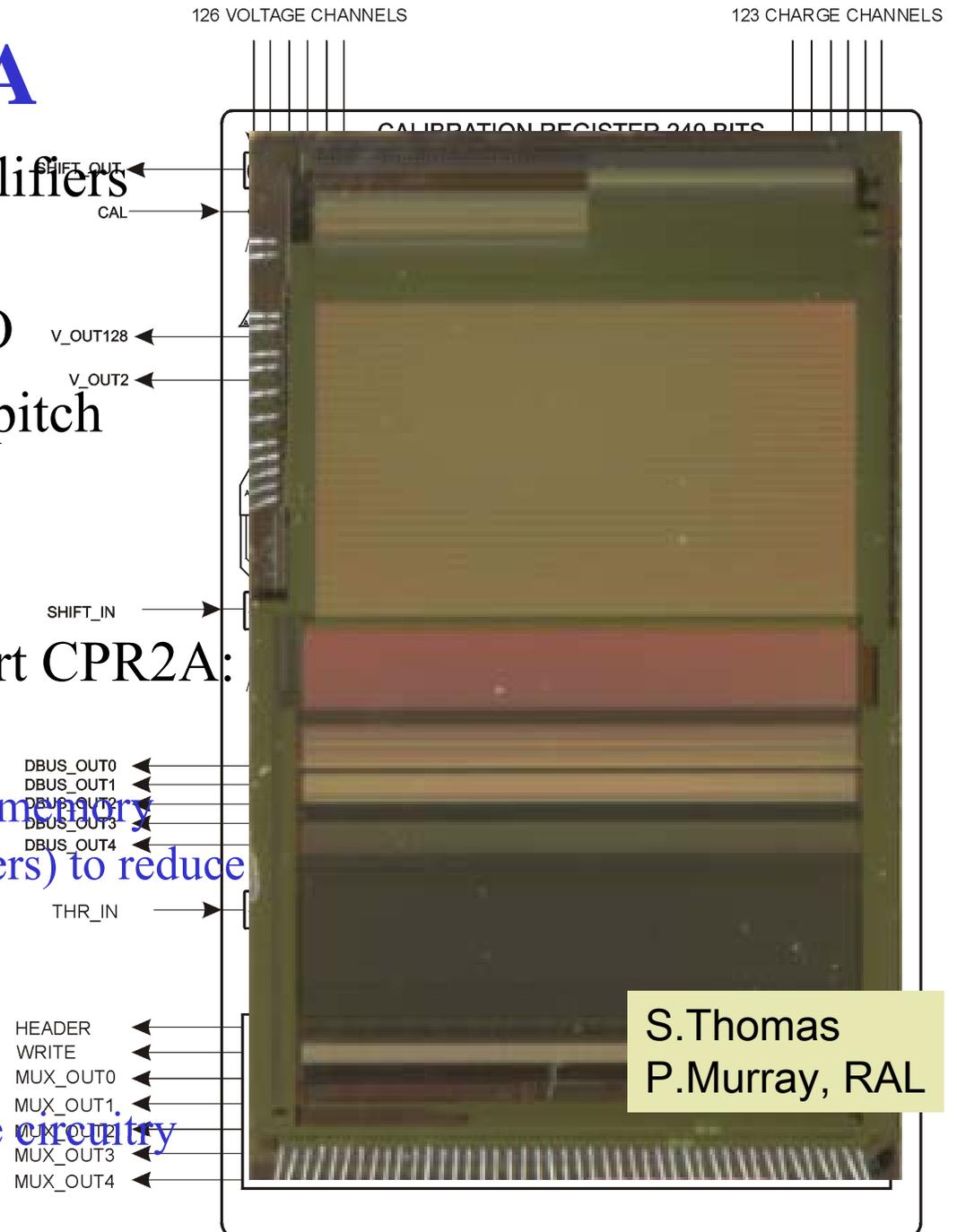
- Low noise operation up to 30 MHz for CPC2-10
  - ◆ 50 MHz within reach
- Limited by substrate bounce effects
  - ◆ Clock pickup at analogue outputs, need to measure amplitude on fast transients
  - ◆ Happens inside CPC2



# **Readout Chip for CPCCD: CPR2A**

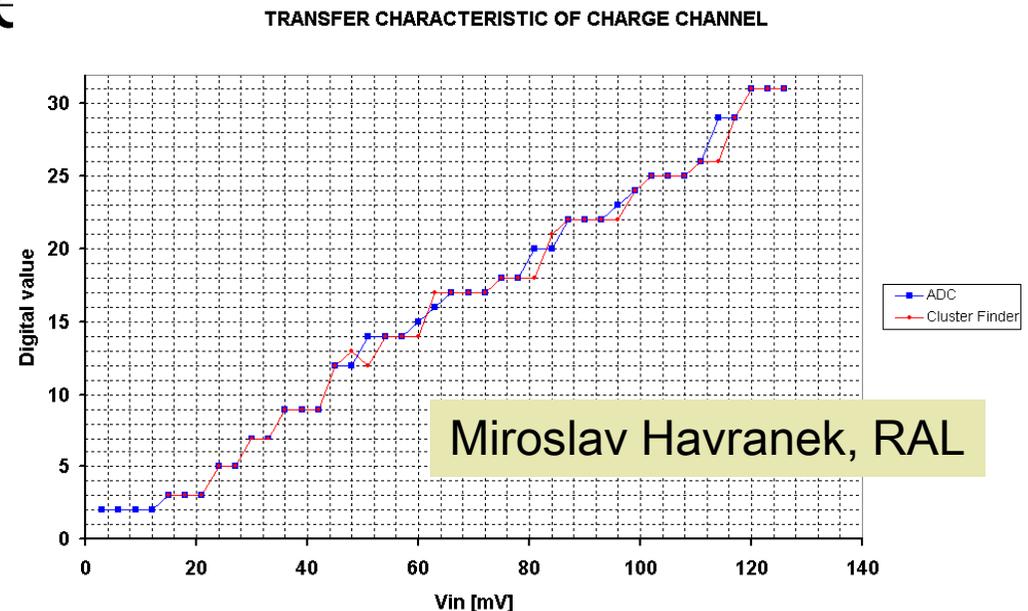
# CPR2A

- 125 voltage and charge amplifiers channels
- Analogue and digital test I/O
- 5-bit flash ADCs on 20  $\mu\text{m}$  pitch
- Cluster finding logic
- Sparse readout circuitry
- A range of improvements wrt CPR2A:
  - ◆ Cluster size reduced to 4x6
  - ◆ 3-fold increase in the column memory buffer (can store up to 3 clusters) to reduce dead time
  - ◆ Individual column threshold
  - ◆ Analogue calibration circuit
  - ◆ Improvements to the analogue circuitry



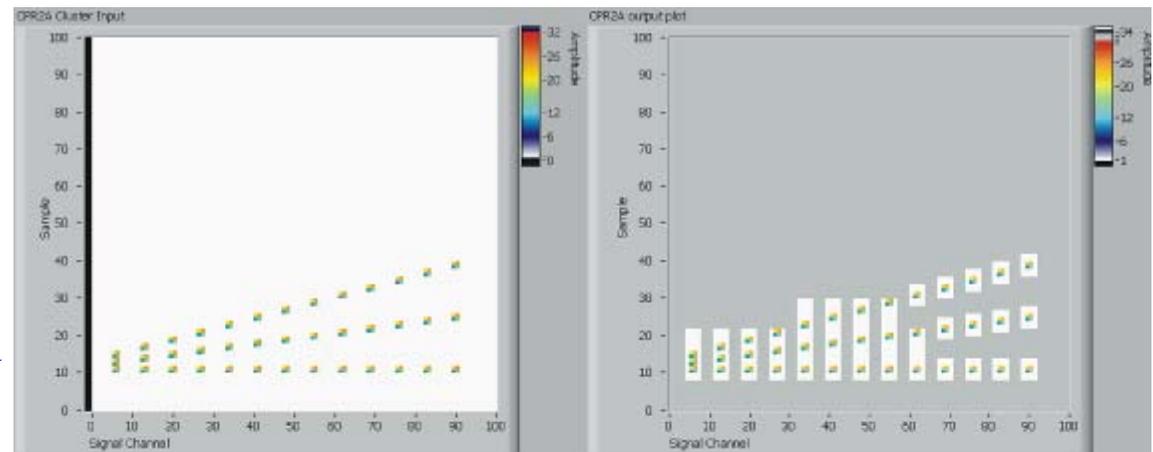
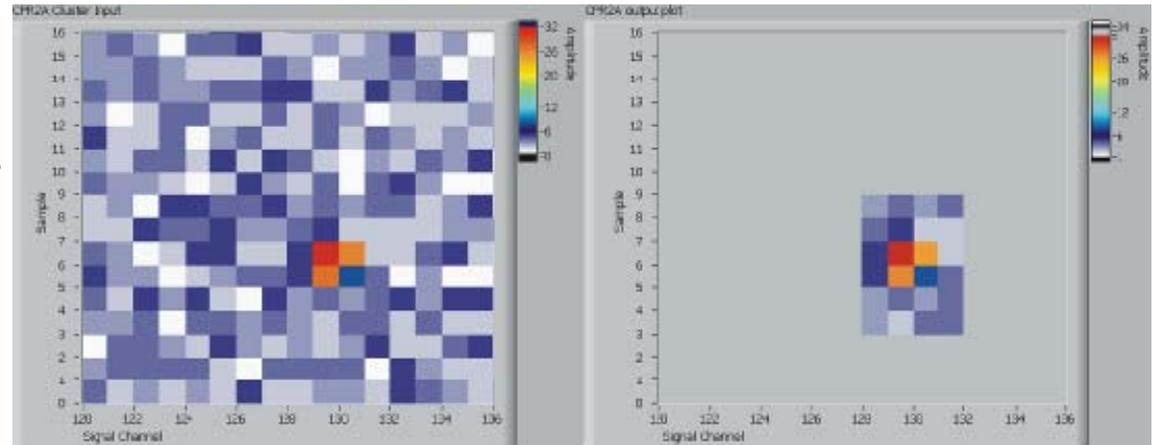
# CPR2A Tests

- Tests started in March 2008
- Simultaneous operation of analogue inputs and cluster finder demonstrated for both voltage and charge amplifiers
- Plot: analogue performance with and without asynchronous cluster finding
  - ◆ Charge amplifiers did not work in CPR2



# CPR2A Cluster Finding

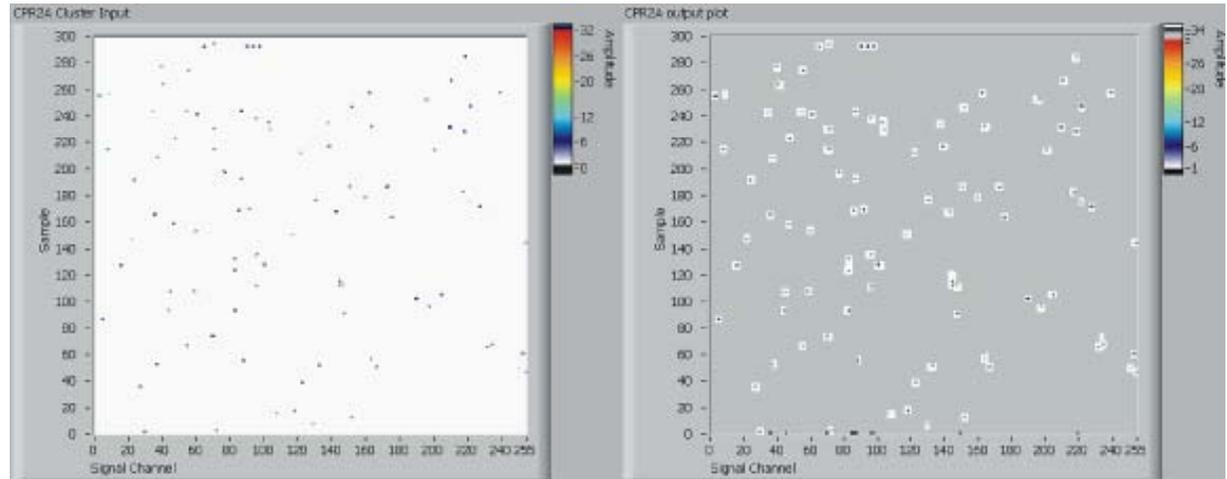
- 2x2 seed cluster
- 4x6 (min size) clusters buffered inside CPR2A
- Cluster finding can be tested both with digital and analogue inputs
  - ◆ Software/firmware effort to code input calibration clusters and analyse data
- Performs up to specs



Miroslav Havranek, RAL

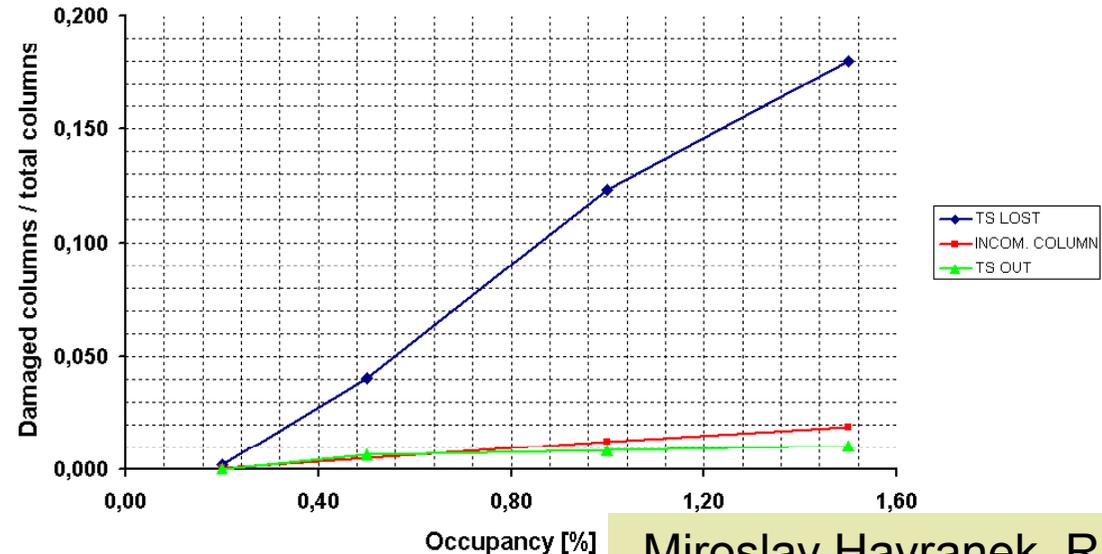
# CPR2A Cluster Finding

- Errors analysed for random distribution of cluster locations
  - ◆ No errors till 0.2% occupancy
  - ◆ Most frequent error is loss of time stamp



ERRORS VS OCCUPANCY

- Overall CPR2A performance is quite impressive and it is ready for CPC2



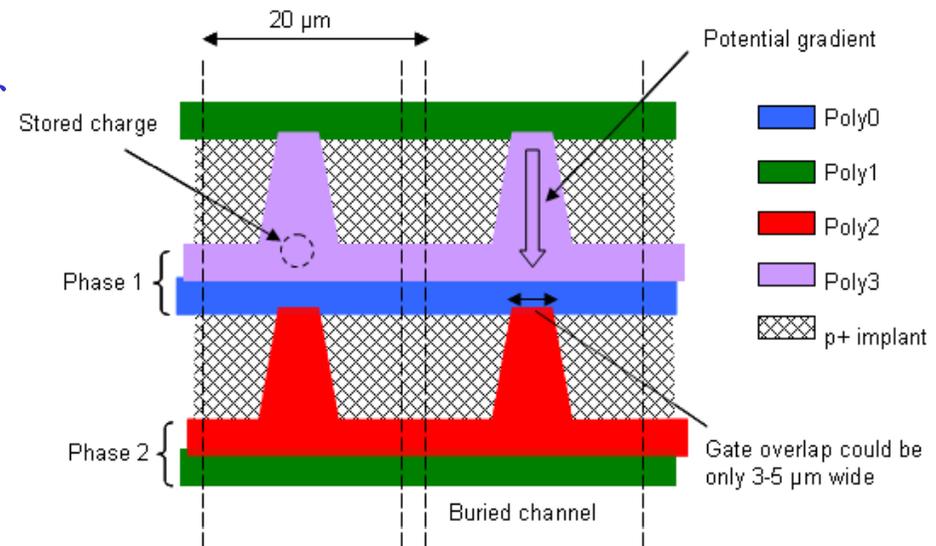
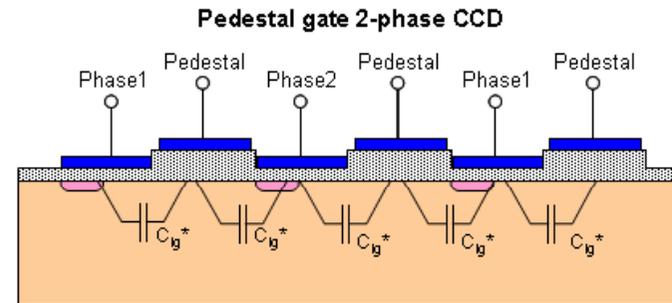
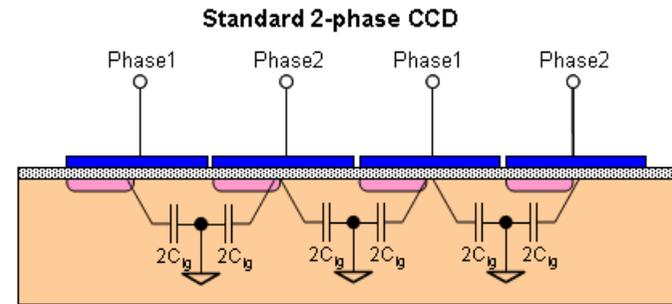
Miroslav Havranek, RAL

Andrei Nomerotski

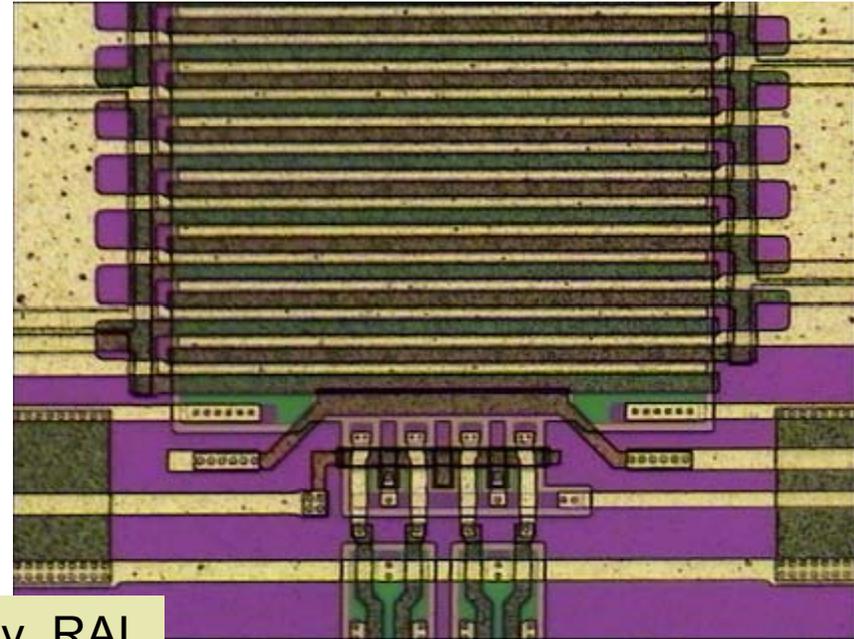
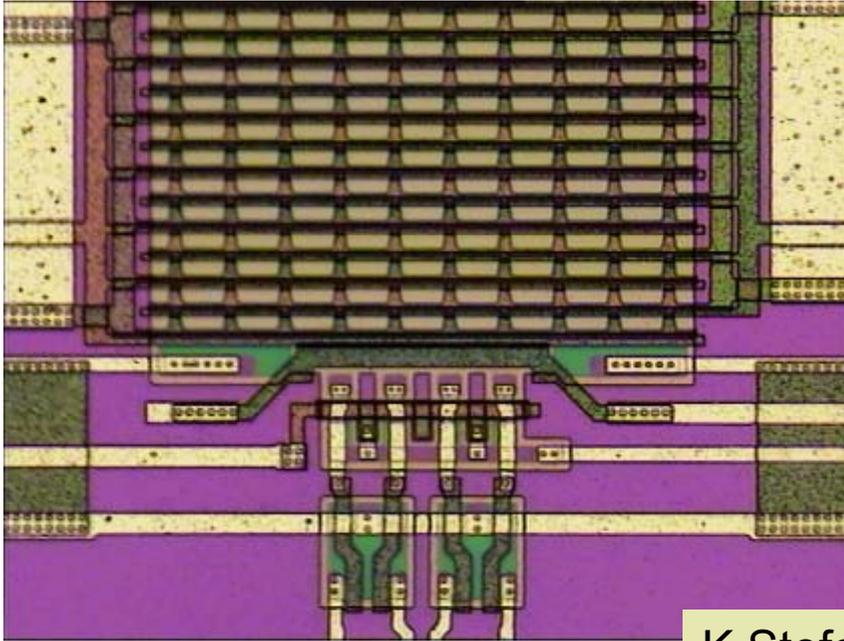
# **CPCCD with reduced capacitance and reduced clock voltage: CPC-T**

# CPC-T

- Two-fold goal : lower  $V$  and lower  $C$
- Two designs based on CPC2 to study very low inter-gate barriers and clock amplitudes
- Six designs for reduction of the inter-gate capacitance:
  - ◆ Pedestal CCD (on 20  $\mu\text{m}$  and 24  $\mu\text{m}$  pitch)
  - ◆ Shaped Channel CCD (variant of the Pedestal CCD), on 20  $\mu\text{m}$  and 24  $\mu\text{m}$  pitch
  - ◆ Open Phase CCD
  - ◆ “Inter-channel gap” CCD
- Pedestal designs could reduce  $C_{ig}$  by a factor of 2-4, open phase by  $\approx 2$



# CPC-T



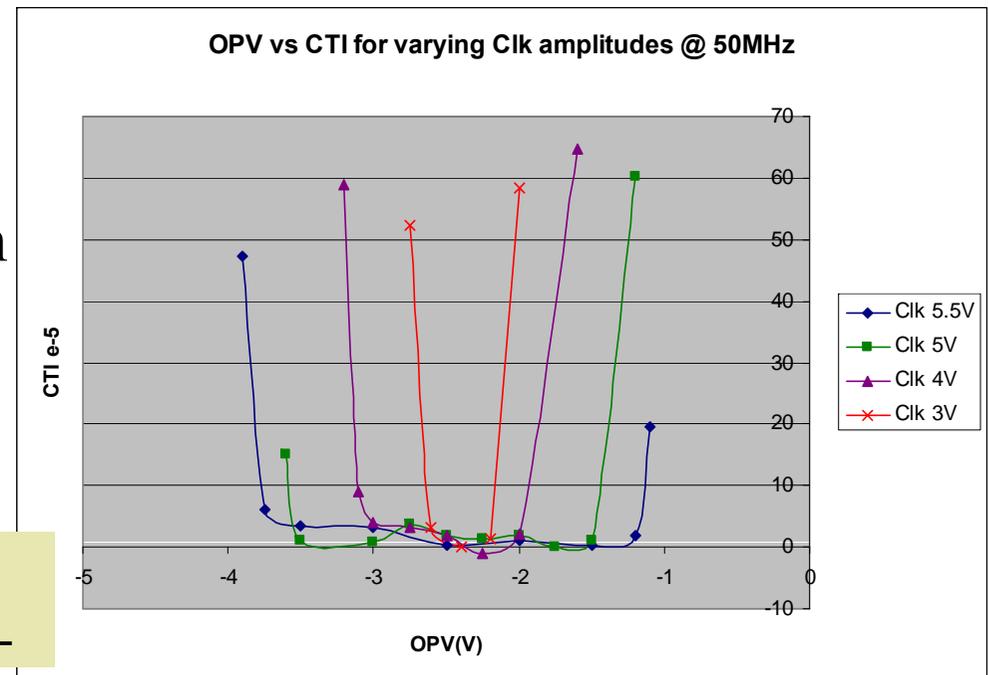
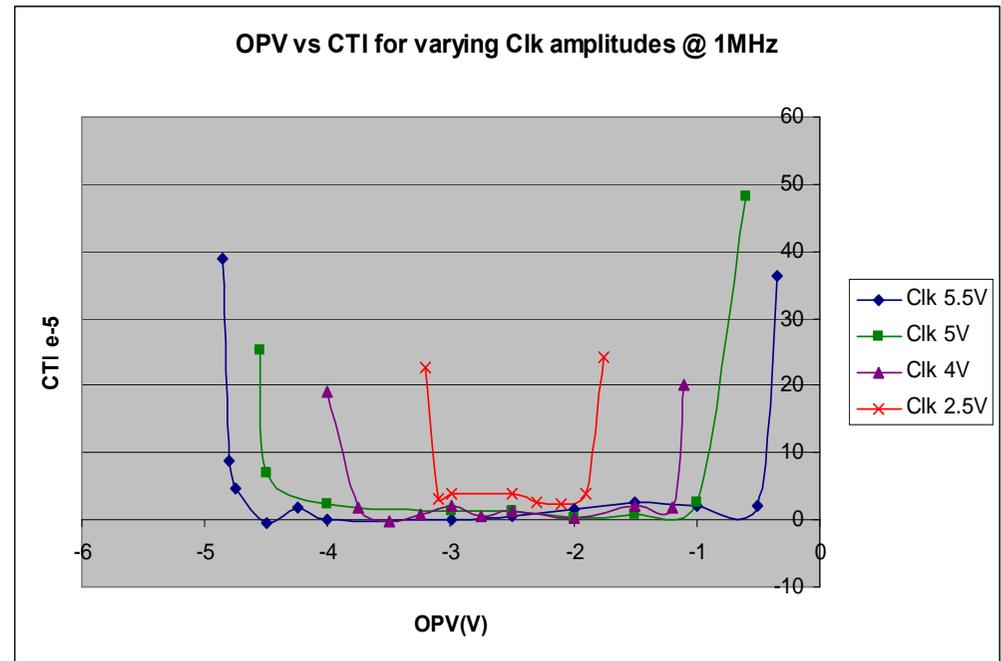
K.Stefanov, RAL

- 6 CPC-T wafers delivered in March 2008, one of each type
  - ◆ One type (stepped nitride barrier) failed for complete wafer

# CPC-T Tests

- 24 variants to test – a lot of work
- 4-phase CCD used to determine the minimal clock amplitude
  - ◆ Look at CTI as function of gate potentials
  - ◆ OPV is voltage difference between two gates of the same phase, emulates implant for 2-phase devices
- 50 MHz operation is no problem
  - ◆ Small device – small C
  - ◆ But need higher clock voltage
  - ◆ Smaller operational OPV range

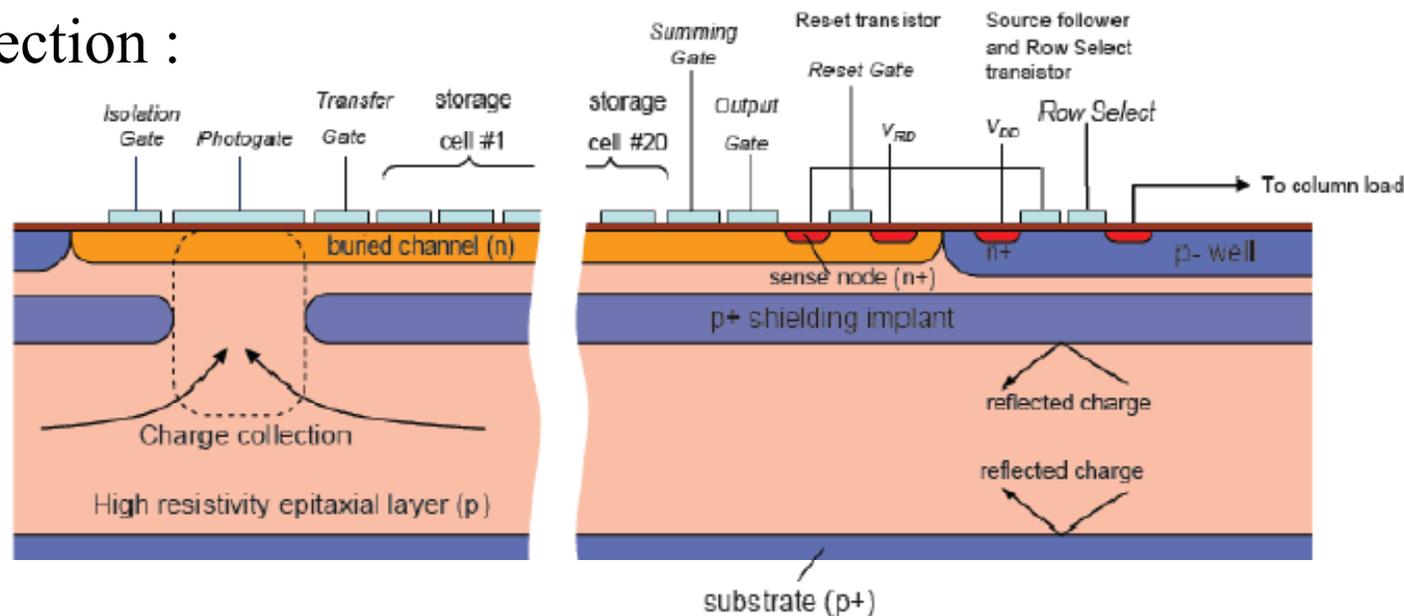
G.Zhang,  
T.Jayawardena, RAL



# ISIS2

# Next generation ISIS: ISIS2

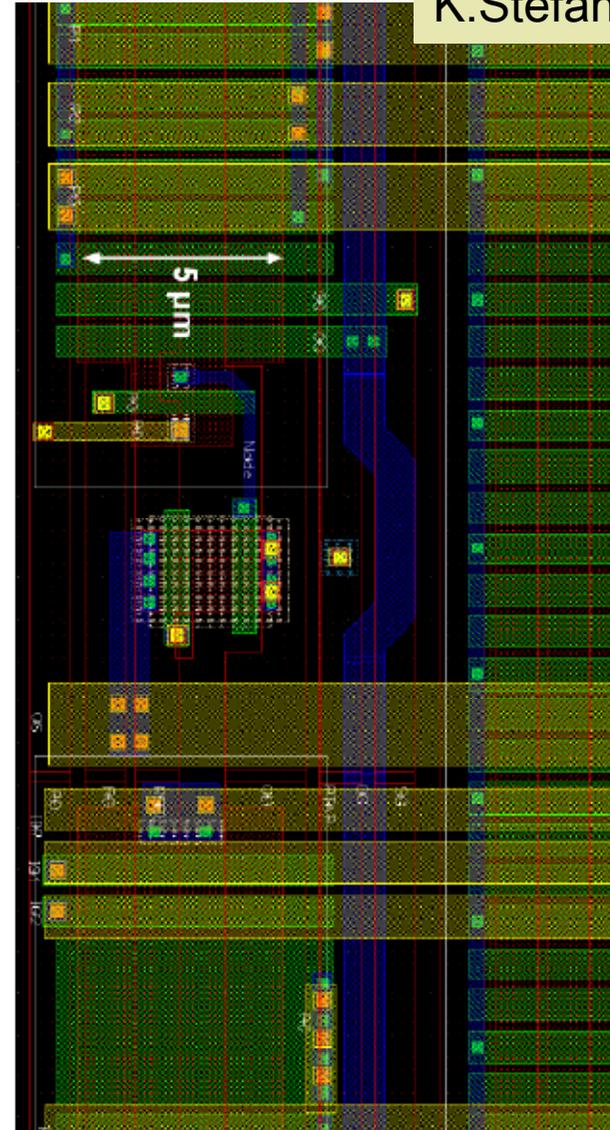
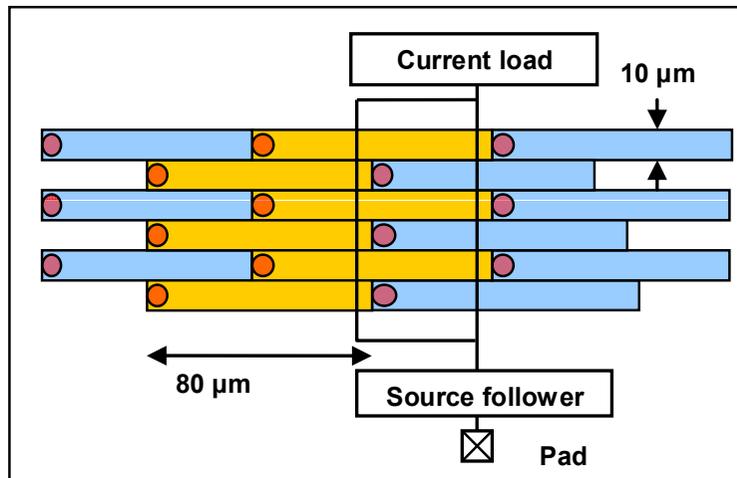
- ISIS2 manufactured by Jazz Semiconductor
- Process: 0.18  $\mu\text{m}$  with dual gate oxide
  - ◆  $p^{++}$  wafers with 25  $\mu\text{m}$  epi layer  $\rho > 100 \text{ Ohm cm}$
- Process enhancement for LCFI: buried channel and deep  $p^+$  implant
  - ◆ Buried channel is necessary for raw charge storage
  - ◆ Deep  $p^+$  protects buried channel from parasitic charge collection
- Cross section :



# ISIS2 Design

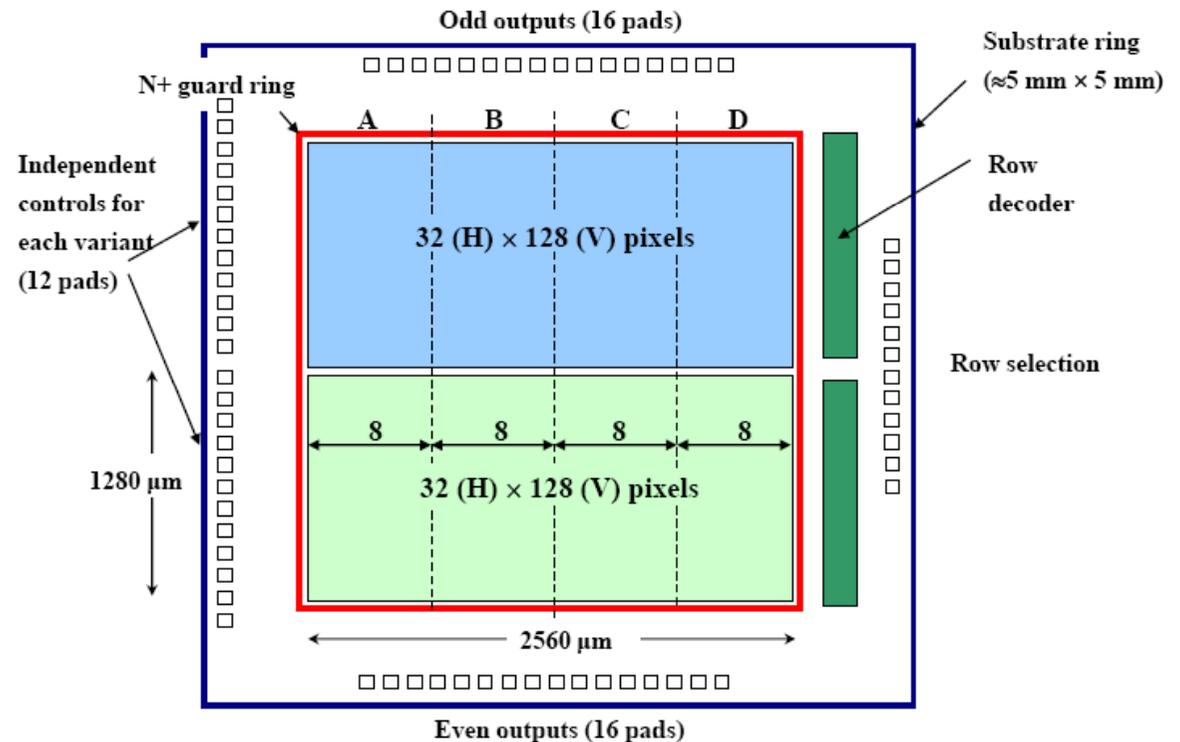
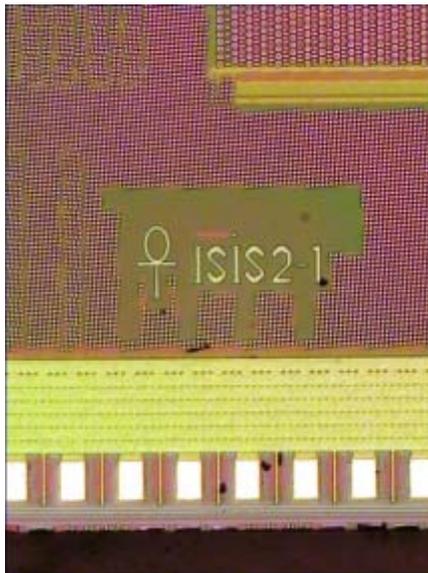
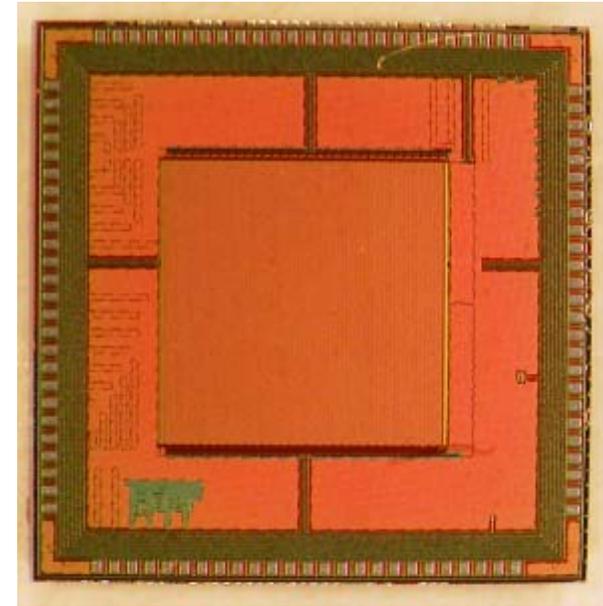
S.Thomas,  
P.Murray,  
K.Stefanov, RAL

- Pixels  $80 \times 10 \mu\text{m}^2$
- Imaging pixels  $40 \times 20 \mu\text{m}^2$
- Buried channel  $5 \mu\text{m}$  wide
- CCD gates: doped polysilicon, non-overlapping
- Logic, source followers use 5V custom logic gates, 3 metal layers



# ISIS2 Design

- One chip will have several variants of ISIS2
  - ◆ Each has independent control
- Row select and decoder edge logic
- Area 1 cm<sup>2</sup> (four 5x5 mm<sup>2</sup> tiles)
- Submitted in May 2008, delivered last week, being packaged



# Summary

- CPCCD demonstrated
  - ◆ Operation at 45 MHz, low noise operation at 30 MHz
  - ◆ Operation with readout chip CPR2 at 9 MHz, new chip CPR2A is a success
  - ◆ Improved CPCCD, CPC-T, are under test
- Raw charge storage demonstrated
  - ◆ Proof of concept ISIS1 tested in beam
  - ◆ Started testing of ISIS2 based on 0.18 um CMOS process
- Future of UK silicon pixel R&D :
  - ◆ New proposal SPIDER (Silicon Pixel DEtector R&D)
  - ◆ Continue ISIS program
  - ◆ Develop MAPS based on 4T process and INMAPS process (deep p+ protective layer)